

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1653	(hydrogen "H.sub.2") near50 plasma near50 (conductive metal copper Cu)	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 08:58
L3	4772529	(via trench hole open\$3 groove recess)	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 08:53
L4	1413	2 and 3	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 06:26
L5	980	4 and (copper Cu)	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 08:53
L7	803	(hydrogen "H.sub.2") near50 plasma near50 (conductive metal copper Cu)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/03/14 08:53
L8	140	7 and (via trench hole open\$3 groove recess)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/03/14 08:53
L9	37	8 and (copper Cu)	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/03/14 08:53
L10	10106	(damascene (dual near5 damascene))	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 10:02
L11	328	10 and ((hydrogen "H.sub.2") near50 plasma near50 (conductive metal copper Cu))	US-PGPU B; USPAT; USOCR	OR	ON	2005/03/14 10:02
L13	3273	(damascene (dual near5 damascene))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/03/14 10:02
L14	19	13 and ((hydrogen "H.sub.2") near50 plasma near50 (conductive metal copper Cu))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/03/14 10:02